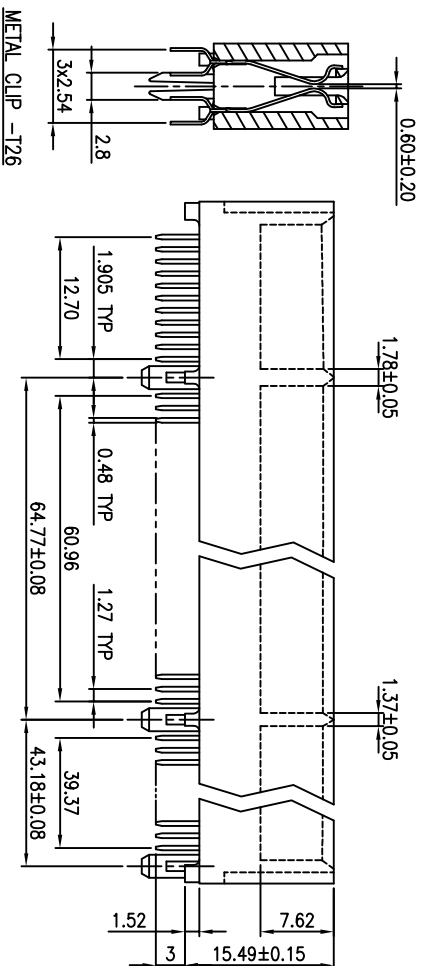
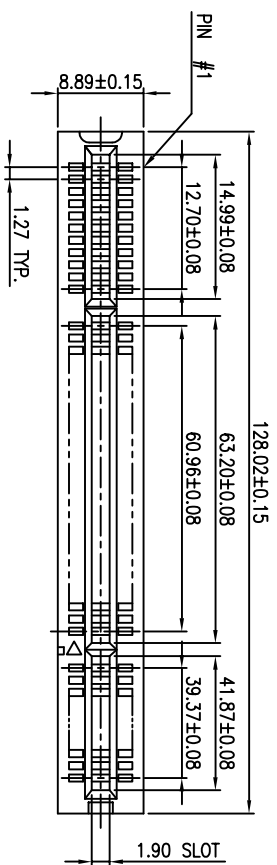


RECOMMENDED PCB LAYOUT

7		8	
REV	DESCRIPTION	BY	DATE
A	Added position 1 indicators	BC	06-03-03

MATERIAL

INSULATOR: GLASS-REINFORCED THERMOPLASTIC,

UL94V-0 RATED.

CONTACT: COPPER ALLOY.

PLATING: MATING AREA- GOLD,

SOLDER AREA-- TIN/LEAD.

ELECTRICAL

VOLTAGE RATING: 250 VAC RMS.

CURRENT RATING: 3 AMP

INSULATION RESISTANCE: 1.000 MEGOHMS MIN.

CONTACT RESISTANCE: 30 MEGOHMS MAX.

MECHANICAL

CONTACT RETENTION: 460 GRAMS MIN PER CONTACT.

INSERTION FORCE: 230 GRAMS MAX PER CONTACT PAIR.

WITHDRAWAL FORCE: 15 GRAMS MIN PER CONTACT PAIR

ENVIRONMENTAL

TEMPERATURE RANGE: -55° TO +85°.

NO PART MARKINGS

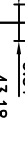
GOLD PLATING

REPLACE "X" IN THE PART NUMBER:

W = SELECTIVE GOLD FLASH

Z = SELECTIVE 10u" GOLD

X = SELECTIVE 30u" GOLD

		UNITS		MM		NAME (INTENDED USE)		SULLINS ELECTRONICS CORP		
MATERIAL		PART NO. (INTENDED USE)		TITLE:		64 BIT PCI CARDEdge, 3.3V				
FINISH		APPD:		PART NO.		TRXB092DKHN-1330/T26				
QTY		CHKD:		SCALE		SHEET		REV		
DRAWN: N. Bozovic		9/23/97		NONE		1 OF 1		A		



SCAL	NON
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SHEET
OF

REV
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